Wire Bond Process

Process Technology
Au, Cu and Al wirebond technology

Au, Cu WireBond Process

- Premium automotive grade wirebond materials
- Ultra Fine Pitch,bond pad pitches as fine as 35 µm.
- Wire sizes from 0.6 mil to 2.5 mil
- Bond placement accuracy of 2.0 µm at 3 sigma.
- Ultra-low loop capability with a minimum height of 40 µm using 0.6 mil wire.
- Enhanced Post-Bond Inspection: Ensures the quality of the bonds with advanced inspection capabilities.

Al WireBond Process

- Large Wire Range: 100µm - 500µm Diameter
- Ribbon Range: 500 x 100µm to 2000 x 250µm
- Small Wire Range: 25µm - 75µm Diameter
- In-line Transport Pulltester, Pull force: 20-500g, non-destructive Up to 4 pulltesters per bonder module
- Loop height check